RF Inductors Soldering and Mounting

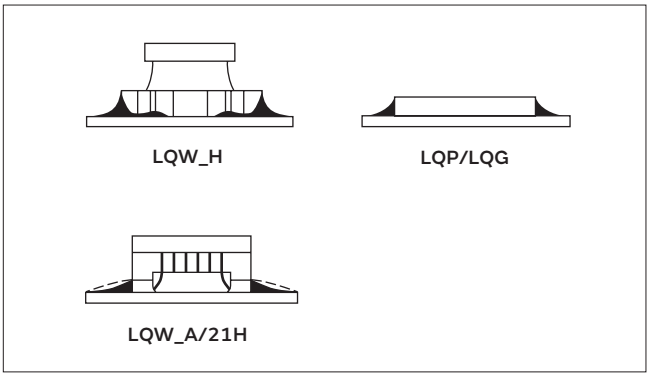
Continued from the preceding page. ↘

(4) Amount of Solder Paste

Excessive solder causes electrode corrosion, while insufficient solder causes low electrode bonding strength. Adjust the amount of solder paste as shown on the right so that the correct amount is applied.

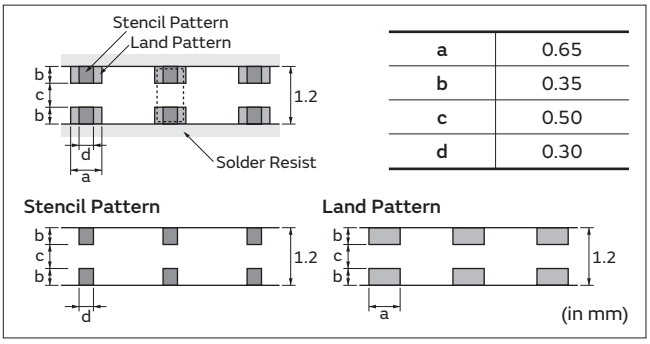
Guideline of solder paste thickness

- LQP (*Except for LQP02TN/LQP02TQ/HQ/ LQP03TQ/HQ),LQG,LQW15AN_00/ LQW15AN_10/LQW18AN/LQW21H/LQW2BA/ LQW2UA: 100 to 150μm
- LQP02TN: 50 to 80μm
- LQP02TQ/HQ: 50 to 65μm
- LQP03TQ/HQ: 100μm
- LQW03A/LQW04A: 80 to 100μm
- LQW15AN_80: 50 to 100μm
- LQW_H: 200 to 300μm



LQW15A Series:

Too much solder may cause slant or rotation of the chip at the time of solder melting. Please reduce the amount of solder by using a smaller solder area than the land pattern, as shown in the figure at right.



a	0.65
b	0.35
c	0.50
d	0.30

4. Cleaning

The following conditions should be observed when cleaning chip inductors (chip coils):

(1) Cleaning Temperature: 60°C max. (40°C max. for alcohol cleaning agents)

(2) Ultrasonic

Output: 20W/l max.

Duration: 5 minutes max.

Frequency: 28 to 40kHz

Care should be taken not to cause resonance of the PCB and mounted products.

(3) Cleaning agent

The following cleaning agents have been tested on individual components. Evaluation in complete assembly should be done prior to production.

(a) Alcohol cleaning agents

Isopropyl alcohol (IPA)

(b) Aqueous cleaning agents

Pine Alpha ST-100S

(4) Ensure that flux residue is completely removed.

Component should be thoroughly dried after aqueous agents have been removed with deionized water.

For additional cleaning methods, please contact Murata.